

**Scott Hatfield**

---

**From:** Dan Mis [dmis@unitive.com]  
**Sent:** Thursday, August 09, 2001 6:24 PM  
**To:** 'shatfield@carolinapatents.com'  
**Subject:** Re: Methods of Forming Metallurgy Structures For Wire and Solder Bond ing And Related Structures

Scott,

We received the docs but I am out of town and will not be back in town until the 20th.

Dan

---

Sent from my BlackBerry Wireless Handheld ([www.BlackBerry.net](http://www.BlackBerry.net))